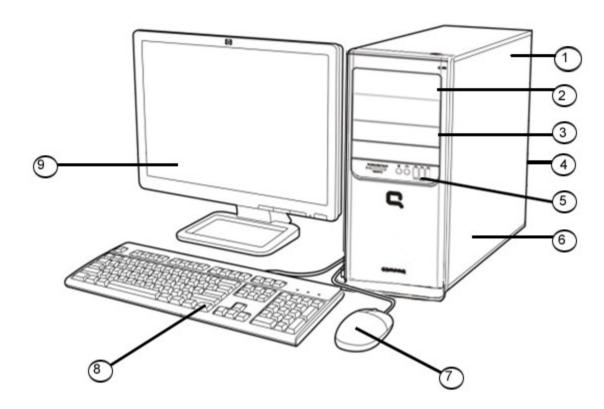
Overview



- 1. 180-watt power supply
- 2. (1) external 5.25-inch bay for optional optical drive
- 3. (1) internal 3.5-inch bay for hard disk drive
- 4. Rear I/O includes (4) USB 2.0 ports, RJ-45 network port, 9. VGA video port, audio in/out jacks, microphone jack
- 5. Front I/O includes (3) USB 2.0 ports, audio in/out jacks, Media Card Reader
- 6. Full height expansion slots include PCIe x1 slots (2)
- 7. Compaq USB Optical Scroll Mouse
- 8. Compag USB Standard Keyboard
- Monitor (sold separately)

At A Glance

- AMD Athlon II X2 Processor
- Choices of Operating systems:
 - Genuine Windows 7 Professional Edition 64*
 - o FreeDOS
- AMD 760G Chipset
- DDR3 SDRAM PC3-10600 (1333 MHz) non-ECC system memory
- ATI Radeon 3000 Graphics
- PCI and PCI Express I/O buses
- Serial ATA controller
- USB 2.0 support
- Realtek RTL8105E 10/100Mbps Ethernet Controller
- Choice of hard drives
- Protected by HP Services. Terms and conditions vary by country. Certain restrictions and exclusions apply.



Standard Features and Configurable Components (availability may vary by country)

Processor and Speed

AMD Athlon II Dual Core Processors with HyperTransport Technology:

One of the following

AMD Athlon II X2 215 Processor (2.7 GHz, 2MB L2 cache, HT bus 3.0)

Operating Systems and Preinstalled Application Software

Genuine Windows 7 Professional Edition 64*

FreeDOS

(availability varies by region)

* System may require upgraded and/or separately purchased hardware and/or a DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See: http://www.microsoft.com/windows/windows-7/ for details.

+ Windows 7 Professional disk may also be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order annually at least 25 customer systems with the same custom image.

2007 Microsoft Office Ready PC

PDF Complete

CyberLink LabelPrint CyberLink Power2Go LightScribe Runtime **HP Vision Diagnostics**

Corel WinDVD

CyberLink Recovery Manager

McAfee Total Protection - Small Business

++ Supporting software available with certain optical drive configurations

Hard Drives

320-GB Serial ATA 3.0-Gb/s NCQ, Smart IV (7200 rpm)

500-GB Serial ATA 3.0-Gb/s NCQ, Smart IV (7200 rpm) 640-GB Serial ATA 3.0-Gb/s NCQ, Smart IV (7200 rpm) 750-GB Serial ATA 3.0-Gb/s NCQ, Smart IV (7200 rpm)

System Memory

2-GB DDR3 Synch DRAM 1333-MHz Non-ECC (2 x 1GB)

2-GB DDR3 Synch DRAM 1333-MHz Non-ECC (1 x 2GB)

3-GB DDR3 Synch DRAM 1333-MHz Non-ECC (1 x 2GB, 1x1GB)

4-GB DDR3 Synch DRAM 1333-MHz Non-ECC (2 x 2GB)

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. The actual memory speed for DDR3 SDRAM depends on the maximum speed supported by the processor; for example, it may be limited to 1066 MHz.

Optical Drive

SATA SuperMulti LightScribe DVD Writer Drive

Input Devices

Keyboard

Compaq USB Standard Keyboard

Mouse

Compaq USB Optical Scroll Mouse



Standard Features and Configurable Components (availability may vary by country)

Audio ALC662-VC1 5.1 channel codec

3D audio compliant and HD Audio compatible

Communication Realtek RTL8105E 10/100Mbps Ethernet Controller

Graphics ATI Radeon 3000 Graphics



System Details

Base Unit

- · Micro ATX microtower chassis, including power supply and front bezel
- Two (2) drive bays and two (2) expansion slots
- Active type heatsink
- System board with AMD 760G chipset, Realtek RTL8105E 10/100 Ethernet controller, ATI Radeon 3000 graphics, and Realtek audio, (2) PCIe x1 slots, (2) DDR3 DIMM memory slots, (4) Serial ATA data connectors
- Product documentation on HDD Image
- HP system restore thru HDD restore
- Power cord

Slots	PCI Memory Expansion	Two (2) full-height PCIe x1 slots Two (2) DDR3 SDRAM DIMM slots (4 GB maximum memory support)		
Bays	Internal	One (1) 3.5"		
	External	One (1) 5.25"		
USB Support	EHCI high-speed USB 2.	0 controller		
	Three (3) front ports; Fou	rts; Four (4) rear ports, Two (2) internal ports on system board		
Interfaces	Front: (3) USB 2.0 ports	, audio in/out jacks		
	Rear : (4) USB 2.0 ports, RJ-45 network port, VGA video port, audio in/out jacks, microphon			
Weight & Dimensions	Chassis Dimensions (H x D x W)	373 x 365 x 165mm 14.68 x 14.37 x 6.49 in		
	Packaged Dimensions (L x H x W)	585 x 498 x 245mm 23.03 x 19.61 x 9.65		
	System Weight	22.4 lb (10.2 kg)		
	Shipping Weight	30.8 lb (14.0 kg)		
Technology and Features	Memory Type	PC3-10600 DDR3 SDRAM (1333MHz) non-ECC Up to 4-GB maximum system memory supported		
	Hard Drive Interfaces Supported	Serial ATA		



Chassis	Front Panel	Power button

Power On LED HDD Activity LED

Cooling Solutions

Supported

Power Supply Fan (variable speed) Active heatsink (variable speed)

Chassis fan

Slots Supported

Two (2) full-height expansion slots (3) USB 2.0 ports, audio in/out jacks

Front I/O Rear I/O

(4) USB 2.0 ports, RJ-45 network port, VGA video port, audio in/out

jacks, microphone jack

Drive Bays One (1) 5-1/4" external

N/A

One (1) 3-1/2" internal

Internal Speaker

Security Padlock loop

Kensington Lock Support

Support for chassis padlocks and cable lock devices

Power Supply 180-watt ATX Power Supply - PFC/non-PFC with a 115v/230v line

switch (varies by country/region)

Unit Environment and Operating Conditions

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 4 in (10.2 cm) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation
 must be provided on the enclosure, and the same operating guidelines listed above will still
 apply.

Temperature Range Operating 32° to 104° F (0° to 40° C)

Non-operating -22° to 149° F (-30° to 65° C)

Relative Humidity Operating 10% to 90% (non-condensing at ambient)

Non-operating 5% to 95% (non-condensing at ambient)

Maximum AltitudeOperating10,000 ft (3048 m)(unpressurized)Non-operating30,000 ft (9000 m)

NOTE: Operating temperature is de-rated 1.0 deg C per 1000 ft (300 m) to 10,000 ft (3000 m) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



System Board

Processor Socket AM3; industry standard Micro ATX form factor

Supports AMD Phenom™ II Quad and Dual Core processors, AMD

Athlon™ II Quad, Triple, and Dual Core processors

PWM ISL6312 - 3 Phase

Chipset AMD 760G Super I/O IT8758E

Front Side Bus Frequency HT3 (up to 5.2GT/s)

Memory DDR3 SDRAM 2 x DIMM slots

Clock Generator SLG8LP625TTR
Integrated Graphics ATI Radeon 3000

Audio ALC662-VC1 5.1 channel codec

LOM Realtek RTL8105E 10/100 Fast Ethernet controller

Storage Four Serial ATA interfaces (hard drive and optical drive)

Expansion Slots 2 x PCle x1 slots BIOS SPI EEPROM

Industrial Standard PCI 2.3 compliant USB 2.0

Rear Side I/O Ports 4 x USB 2.0 ports

1 x RJ-45 10/100 port

1 x D-sub 15 pin analog VGA port

3 x audio ports

On Board I/O Interfaces 1 x ATX power connector

1 x +12V power connector

1 x Front panel connector, Switch, LED (ON/Flash/OFF)

2 x Fan headers for CPU, chassis, with voltage/fan speed control

1 x header to support 2 USB 2.0 ports at front side 1 x header to support 2 front (Headphone/Mic) audio ports

1 x header to support USB media reader

Board Size Micro-ATX, PCB Size: 9.6 x 9.6 in (24.38 x 24.38 cm)

4-layer PCB with green color

Additional Features

Bootable without keyboard, mouse or monitor

Keyboard/mouse/USB wake up

Support S3, S4 and S5

ACPI status

Hardware monitor capability

CPU fan speed control

Network Interface

Integrated Realtek
RTL8105E 10/100 Fast
Ethernet Controller

Hardware Highlights

Features

PCIe x1 interface

10-Mbps and 100-Mbps operation Crossover detection and auto-correction Wake-on-Lan and remote Wake-up (Wakeon-LAN supported from S3, S4 only. Not

supported from S5)



Power Supply

- ATX Power Supply Passive PFC/non-PFC with a 115v/230v line switch
- Passive Power Factor Correction (PFC) with line switch set to 230V No PFC in 115V line switch position
- 90 to 140VAC, or 180 to 264VAC operating voltage range
- 100 to 127VAC, or 200 to 240VAC rated voltage range
- 50-60 Hz rated line frequency
- 47-63 Hz operating line frequency range
- 180 watt maximum rated power
- 80-mm power supply fan variable speed for optimum acoustics

Power Conservation 'Energy Saver'

- APM 1.2 support
- Screen blanking
- Hard drive 'Idle' mode
- System Idle mode
- ~2 watt power consumption in ES mode suspend to RAM (S3) (instantly available PC)
- Processor/Cache memory power-down (S3)
- Eup Lot 6 less than 1W with BIOS setup option (Max power savings)

System Environmental Specs

- Values are subject to change without notification and are for reference only.
- Performance of system, options, and ancillary equipment will vary depending on the system configuration.
- Levels presented do not account for non-HP/Compag installed hardware

Ambient Air	ted do not account for non-HP/Compaq installed hardware.		
Temperature	Operating	32° to 104° F (0° to 40° C) at sea level with an altitude de-rating of 1.0°C per every 1000 ft (300 m) above sea level to a maximum of 8000 ft (2500 m), no direct sustained sunlight. Maximum rate of change is 77°F/Hr (25°C/Hr). The upper limit may be limited by the type and number of options installed.	
	Storage	-22° to 149° F (-30° to 65° C) Maximum rate of change: 410°F/Hr (210°C/Hr).	
Humidity	Operating	10% to 90% relative humidity (Rh), 86°F (30°C) maximum wet bulb temperature, noncondensing.	
	Storage	10% to 95% relative humidity (Rh), 101.66°F (38.7°C) maximum wet bulb temperature, non-condensing.	
Altitude	Operating	0 to 10,000 feet (0 to 3048 meters) - This value may be limited by the type and number of options installed. Maximum allowable altitude change rate is 1,000 ft/min (304.8 m/min).	
	Non-Operating	0 to 30,000 feet (0 to 9,144 meters) - Maximum allowable altitude change rate is 1200 ft/min (365.76 m/min).	
Shock	Listed are the levels of shock the product can withstand with NO damage being incurred. The values represent peak input acceleration during a 2 to 3 ms half-sine shock pulse, 11 ms trapezoidal shock pulse.		
	Non-Operating	35G's (Half-sine Shock) 35G's (Trapezoidal Shock)	
Vibration	Listed are the levels of vibration the product can withstand with NO		

damage being incurred. The values represent a flat random vibration

input acceleration profile across the given frequency range.



Operating Random vibration at 5Hz@0.00025G²/Hz,

10Hz@0.01G2/Hz. 100Hz@0.01G2/Hz.

300Hz@0.00001G2/Hz

5Hz to 300Hz, (0.25G's nominal).

Non-Operating Random vibration at 0.008G²/Hz,

10Hz to 500Hz, (2 Grms nominal).

Service and Support

On-site Warranty^{Note 1}: One-year (1-1-0) limited warranty delivers one year of on-site; (1-1-1) on selected countries, next business-day^{Note 2} service for parts and labor and includes free telephone support^{Note 3} 24 x 7. Global coverage^{Note 2} ensures that any product purchased in one country and transferred to another non-restricted country will remain fully covered under the original warranty and service offering. One-year onsite and labor are not available in all countries.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured Compaq and third-party HP-qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.



Memory

DDR SYNCH DRAM NON-ECC MEMORY

AMD 760G chipset supports non-ECC DDR3 memory up to PC3-10600 (1333-MHz). Memory upgrades are accomplished by adding single or dual DIMMs of the same or varied sizes. This chart does not represent all possible memory configurations.

CAUTION: You must shut down the computer and **disconnect the power cord** before adding or removing memory modules. Regardless of the power-on state, voltage is always supplied to the memory modules as long as the computer is plugged in to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board.

HP recommends dual-channel symmetric configurations for maximum performance.

For best performance, add the same amount of total memory to each channel and do not mix speeds. For dual-channel symmetric performance, the total amount of memory in each channel must be equal. If speeds are mixed, speed will default to the slowest DIMM.

STANDARD MEMORY

1-GB, 2-GB, 3-GB or 4-GB DDR3 SYNCH DRAM

OPTIONAL MEMORY UPGRADES

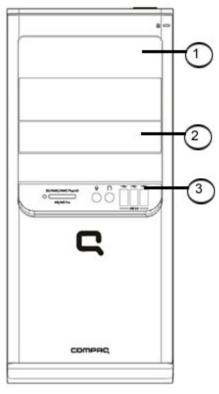
Supports up to 4 GB of DDR3 SYNCH DRAM. Not all memory configurations possible are represented below.

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

DIMM Size	Slot 1	Slot 2
1-GB	1-GB	
2-GB (dual-channel symmetric)	1-GB	1-GB
3-GB	1-GB	2-GB
3-GB	2-GB	1-GB
4-GB (dual-channel symmetric)	2-GB	2-GB



Storage



- 1. Optical Drive
- 2. 3.5" Serial ATA Hard Drive
- 3. Front I/O

Maximum Quantity Supported	Controller
1	SATA
1	SATA
3	USB 2.0 port
1	Media Reade



Technical Specifications - Audio

Integrated Realtek ALC662 Audio

Type Integrated
HD Audio compatible Yes

codec 5:1 channel

Sampling Supports 48/96 KHz

Audio Jacks Mic-In

Line-In

Line-Out / Headphone Out

Power Support Digital: 3.3V

Analog: 5V

Other Meets performance requirements for audio on PC99/2001 systems

High-performance DACs with 97dB SNR(A-Weighting)

ADCs with 90dB NR(A-Weighting)



Technical Specifications - Communications

Integrated Realtek RTL8105E 10/100 Fast Ethernet Controller Controller 8105E Memory N/A

Data rates supported2.5GHz data rate with X1 link widthComplianceIEEE802.3, IEEE 802.3u, IEEE 802.3ab

Bus architecture PClexpress 1.1

Data transfer mode Half/Full Duplex Operation

Hardware certifications MS NDIS5, IPv4, Ipv6, TCP, UDP

Boot ROM support EEPROM, 1Kb, 2Kb

Network transfer rate 10/100Mbps over CAT.5

10Mbps over CAT.3

Dimensions 9mm x 9mm

Management ACPI rev 2.0, PM rev 1.1, ASPM v1.0a capabilities



Technical Specifications - Input Devices

Compaq USB Standard Physical Keys 104, 105, 106, 107, 109 layout (depending Kevboard characteristics upon country)

Dimensions (L x W x H) 18.14 x 1.07 x 6.02 in (46.1 x 2.74 x 15.3 cm)

Weight 1.3lb(0.6 kg) minimum

Electrical Operating voltage + 5VDC ± 5%

> **Power consumption** 50-mA maximum (with three LEDs ON)

ESD CE level 4, 12.5-kV air discharge EMI - RFI Conforms to FCC rules for a Class B

computing device

Microsoft PC 99 - 2001 Functionally compliant

Mechanical 40 available Languages

Keycaps Silm design

Switch actuation 60-g nominal peak force with tactile feedback Switch life 10 million keystrokes (using Hasco modified

tester)

Switch type Contamination-resistant switch membrane

Key-leveling N/A

mechanisms

Cable length 1.5 m

Microsoft PC 99 - 2001 Mechanically compliant

Acoustics 50-dBA maximum sound pressure level

Environmental Operating temperature 50° to 122° F (10° to 50° C)

Non-operating

temperature

-22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient) Non-operating humidity20% to 80% (non-condensing at ambient)

Operating shock 40g, six surfaces Non-operating shock 80g, six surfaces Operating vibration 2-g peak acceleration Non-operating

vibration

4-g peak acceleration

Drop (out of box) 30 in (76 cm) on carpet, 5-drop sequence **Drop** (in box) 30 in (76 cm) on rigid surface, 10-drop

sequence

ULcUL, FCC, CE, TUV/Bauart, VCCI, BSMI, C-Tick, KCC **Approvals**

Ergonomic compliance N/A



Technical Specifications - Input Devices

Compaq USB 2-Button Scroll Wheel **Optical Scroll Mouse**

24

Maximum Rotation

Speed

Mechanical

48 rats/sec

Switch Type wheel

Switch Life Button - 1,000,000

Wheel - 200,000 times

Environmental Operating Temperature 32° to 104° F (0° to 40° C)

Non-operating

-4° to 140° F (-20° to 60° C)

Temperature

Operating Humidity 10% to 90% (non-condensing at ambient) Non-operating 20% to 80% (non-condensing at ambient)

Humidity

Operating Shock 40 g, six surfaces **Non-operating Shock** 80 g, six surfaces **Operating Vibration** 2-g peak acceleration Non-operating 4-g peak acceleration

Vibration

Electrical Operating Voltage 4.35V-5.25V DC

> **Power Consumption** <100mA **MTBF** > 150,000 hrs

ESD IEC-61000-4-2 criteria B, Contact discharge:

+/- 4kV, Air discharge: +/- 8kV

EMI-RFI FCC Class B **PC98** PC 99 Compliant 500±10% DPI Resolution

Tracking Speed 25 cm/sec Acceleration 0.5mm **Switch Actuation** 0.6N (60gf)

Switch Life Button - 1,000,000 Wheel - 200,000 times

Cable Length 1.8m

PC98-99 PC99 compliant

Regulatory Approvals ULcUL, FCC, CE, TUV/GS, VCCI, BSMI, C-Tick, MIC



Technical Specifications - Hard Drives

Serial ATA Hard Drives 750 GB

(7200 rpm)

Capacity 720,176,893,706 bytes

Height 1 in (2.54 cm)

Width Media diameter: 3.5 in (8.89 cm)

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer 3.0 Gb/s

Rate (Maximum)

Buffer 8 MB

Seek Time (typical
reads, includes controller
overhead, including
settling)Single Track
Average2.0 msAverage
Full-Stroke11 ms2.1 ms

Rotational Speed 7,200 rpm Logical Blocks 976,773,168

Operating Temperature41° to 131° F (5° to 55° C)

640 GB Capacity 640,138,063,380 bytes

Height 1 in (2.54 cm)

Width Media diameter: 3.5 in (8.9 cm)

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer Up to 3 Gb/s

Rate (Maximum)

Buffer 8 MB

Seek Time (typical
reads, includes controller
overhead, including
settling)Single Track
Average2.0 msAverage
Full-Stroke11 ms2.1 ms

Rotational Speed 7,200 rpm **Logical Blocks** 625,142,448

Operating Temperature41° to 131° F (5° to 55° C)

500 GB Capacity 500,107,862,016 bytes

Height 1 in (2.54 cm)

Width Media diameter: 3.5 in (8.89 cm)

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer 3.0 Gb/s

Rate (Maximum)

Buffer 8 MB

Seek Time (typical
reads, includes controller
overhead, including
settling)Single Track
Average2.0 msAverage
Full-Stroke11 ms2.1 ms

Rotational Speed 7,200 rpm Logical Blocks 976,773,168

Operating Temperature41° to 131° F (5° to 55° C)

320 GB Capacity 320,072,933,376 bytes



Technical Specifications - Hard Drives

Height 1 in (2.54 cm)

Width Media diameter: 3.5 in (8.9 cm)

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer Up to 3 Gb/s

Rate (Maximum)

Buffer 8 MB

Seek Time (typical
reads, includes controller
overhead, including
settling)Single Track
Average2.0 msAverage
Full-Stroke11 ms2.1 ms

Rotational Speed 7,200 rpm **Logical Blocks** 625,142,448

Operating Temperature41° to 131° F (5° to 55° C)



Technical Specifications - Optical Storage

(all conditions

non-condensing)

HP SATA SuperMulti	Height	5.25-inch, half-height, tra	y-load	
LightScribe DVD Writer Drive		Either horizontal or vertical		
	Interface type	SATA/ATAPI		
	Disc capacity	8.5 GB DL or 4.7 GB standard		
	Dimensions (W x H x D) 5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)			
	Weight (max)	2.6 lb (1.2 kg)		
	Write speeds	DVD-RAM	Up to 12X	
		DVD+R	Up to 16X	
		DVD+RW	Up to 8X	
		DVD+R DL	Up to 8X	
		DVD-R DL	Up to 8X	
		DVD-R	Up to 16X	
		DVD-RW	Up to 6X	
		CD-R	Up to 48X	
		CD-RW	Up to 32X	
	Read speeds	DVD-RAM	Up to 12X	
		DVD+R/-R/+RW/ -RW/+R DL /-R DL	Up to 8X	
		DVD-ROM DL	Up to 8X	
		DVD-ROM, DVD+R, DVD-R	Up to 16X	
		CD-ROM, CD-R	Up to 48X	
		CD-RW	Up to 32X	
	Access times (typical reads, including	Random	DVD: < 140 ms (typical), CD: < 125 ms (typical)	
	setting)	Full Stroke	DVD: < 250 ms (seek), CD: < 210 ms (seek)	
	Power	Source	SATA DC power receptacle	
		DC Power Requiremen	nt5 VDC ± 5%-100 mV ripple p-p 12 VDC ± 5%-200 mV ripple p-p	
		DC Current	5 VDC - <1000 mA typical, < 1600 mA maximum 12 VDC -< 600 mA typical, < 1400 mA maximum	
	Environmental	Temperature	41° to 122° F (5° to 50° C)	
	/ = 11 1141			



Relative Humidity

Temperature

Maximum Wet Bulb

10% to 90%

86° F (30° C)

Technical Specifications - Environmental Data

Eco-Label Certifications and declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

Energy Consumption	115 VAC	230 VAC	100 VAC
Normal Operation	37.40 W	37.00 W	NA
Sleep (low power mode)	3.19 W	3.25 W	NA
Off	1.77 W	1.83 W	NA
Heat Dissipation*	115 VAC	230 VAC	100 VAC
Normal Operation	128 BTU/hr	127 BTU/hr	NA
Sleep	11 BTU/hr	11 BTU/hr	NA
Off	6 BTU/hr	6 BTU/hr	NA

^{*} Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions

(in accordance with ISO 7779 and ISO 9296)

	Sound Power	Sound Pressure
System Fan Off	(LWAd, bels)	(LpAm, decibels)
Idle	4.2	30
Fixed Disk (random writes)	4.5	33

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- · Mercury greater the 5ppm by weight
- Cadmium greater than 10ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2002/95/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.
- This product contains 0% post consumer recycled plastic (by wt.)
- This product is 90% recyclable when properly disposed of at end of life.

Packaging Materials

- External:
 - Corrugated 1680 g
- Internal:
 - o EPE- Expanded Polyethylene 115 g
 - O Polyethylene low density 40 g
- The Corrugated packaging material is made from 80% recycled content.
- The EPE- Expanded Polyethylene packaging material is made from 80% recycled content.
- The Polyethylene low density packaging material is made from 80% recycled content.

RoHS Compliance

Hewlett-Packard is committed to compliance with all applicable environmental laws and



Technical Specifications - Environmental Data

regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. By July 1, 2006, RoHS substances will be virtually eliminated (virtually = to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption under the EU RoHS Directive).

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at:

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehvde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
- Nickel finishes that release greater than 0.5 micro-grams/cm²/week, measured according to EN 1811:1998, are not used on any product surface designed to be frequently handled or touched by users.

Packaging

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Hewlett-Packard Corporate **Environmental**

For more information about HP's commitment to the environment: Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html



Technical Specifications - Environmental Data

Information Eco-label certifications

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html

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